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#### **PRODUCTION DATA SHEET**

### **DESCRIPTION**

The LX5250/52 is a multimode SCSI terminator that is compatible with the SCSI SPI-2 (Ultra2 SCSI), SCSI SPI-3 (Ultra3 SCSI or Ultra160 SCSI), and SCSI SPI-4 (Ultra320) specifications developed by the T10 standards committee for low voltage differential (LVD) termination, while providing backwards compatibility to the SCSI, SCSI-2. and SPI single-ended specifications. Multimode compatibility permits the use of legacy devices on the without hardware alterations. Automatic mode selection is achieved through voltage detection on the Diffsense line.

The LX5250/52 utilizes an industry standard LVD architecture. The individual high bandwidth drivers maximize channel separation, reduce channel-to-channel noise and cross talk to insure Ultra320 performance.

When the LX5250/52 is enabled, the differential sense (DIFFSENSE) pin supplies a voltage between 1.2V and

1.4V. In application this pin is tied to the DIFFSENSE input of the corresponding LVD transceivers. This action enables the LVD transceiver function. DIFFSENSE is capable of supplying a maximum of 10mA.

Tying the DIFFSENSE pin high places the LX5250/52 in a HI Z state indicating the presence of an HVD device. Tying the pin low places the part in a single-ended mode while also signaling the multimode transceiver to operate in a single-ended mode.

Recognizing the needs of portable and configurable peripherals, the LX5250/52 has a TTL compatible sleep/disable mode. During this sleep/disable mode, power dissipation is reduced to a meager 15uA while also placing all outputs in a HI Z state. Also during sleep/disable mode, the DIFFSENSE function is disabled and is placed in a HI Z state.

The LX5250/52 also provides a master / slave function. Driving this pin high or floating the pin enables the 1.3V DIFFSENSE reference. Driving the pin low disables the on board DIFFSENSE reference and enables use of an external master reference device.

**IMPORTANT:** For the most current data, consult *MICROSEMI*'s website: http://www.microsemi.com

### **KEY FEATURES**

- Compliant with SCSI SPI-2 (Ultra2), SPI-3 (Ultra160), and SPI-4 (Ultra320)
- Auto-Selectable LVD or Single-Ended Termination
- Fast Response, No Output Capacitors Required
- Compatible with Active Negation Drivers
- 15µA Supply Current in Disconnect Mode
- Logic Command Disconnects All Termination Lines
- Diffsense Line Driver
- Ground Driver Integrated for Single-Ended Operation
- Current Limit and Thermal Protection
- Hot-Swap Compatible (Single-Ended)
- Available in 36-pin QSOP and 28pin TSSOP package
- LX5250, 36-pin QSOP: Pin Compatible With DS2118, UCC5630A and UCC5672
- LX5250 28-pin TSSOP: Pin Compatible with DS2119, and UCC5672



PACKAGE ORDER INFO					
T <sub>A</sub> (°C)	DB QSOP 36-Pin	TSSOP 28-Pin			
1A ( C)	RoHS Compliant / Pb-free Transition DC: 0535	RoHS Compliant / Pb-free Transition DC: 0518			
0 to 70	LX5250CDB LX5252CDB	LX5250CPW -			

Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX5250CDB-TR)



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### ABSOLUTE MAXIMUM RATINGS

Term Power (V <sub>TERM</sub> )	0.3V to 7V
Operating Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
RoHS / Pb-free Peak Package Solder Reflow Temperature	
(40 second maximum exposure)	260°C (+0, -5)

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

### THERMAL DATA

DB 36 Pin QSOP

THERMAL RESISTANCE-JUNCTION TO AMBIENT,  $\theta_{JA}$ 

53.9°C/W

PW 28 Pin TSSOP

THERMAL RESISTANCE-JUNCTION TO AMBIENT,  $\theta_{JA}$ 

100°C/W

Junction Temperature Calculation:  $T_J = T_A + (P_D \times \theta_{JA})$ .

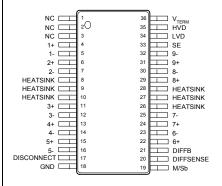
The  $\theta_{JA}$  numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.  $\theta_{JA}$  can vary significantly depending on mounting technique. (See Application Notes Section: Thermal considerations)

### MASTER/SLAVE FUNCTION TABLE

Master/Slave	DIFFSE	ENSE Status
L*	HI Z	0mA
Н	1.3V	10mA Source
Open (Pull-Up)	1.3V	10mA Source

<sup>\*</sup> When in Low state, terminator will sense state of DIFFSENSE line.

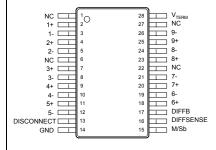
### PACKAGE PIN OUT



#### LX5250/5252

**DB PACKAGE** (Top View)

N/C = Not internally connected



### LX5250 ONLY

PW PACKAGE (Top View)

N/C = Not internally connected

RoHS / Pb-free 100% Matte Tin Lead Finish

DIFFSENSE/POWER UP/POWER DOWN FUNCTION TABLE						
LX5250	LX5252	DIFFSENSE	Outputs		Quiescent	
DISCONNECT	DISCONNECT	DIFFSENSE	Status	Туре	Current	
L	Н	< 0.5V	Enable	SE	55mA	
L	Н	0.7V - 1.9V	Enable	LVD	35mA	
L	Н	> 2.4V	Disable	HI-Z	8mA	
H or Open	L or Open	Х	Disable	HI-Z	10μΑ	



#### PRODUCTION DATA SHEET

## RECOMMENDED MAX OPERATING CONDITIONS

Parameter	Symbol	LX5250/52			Units
Faranietei	Syllibol	Min	Тур	Max	Units
LVD LVD	V	2.9		5.25	\/
VTerm SE	V <sub>TERM</sub>	3.5		5.25	V
Signal Line Voltage		0		5.0	V
Disconnect Input Voltage		0		$V_{TERM}$	V
Operating Junction Temperature	T <sub>J</sub>	0		125	°C

#### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified, the following specifications apply over the operating ambient temperature  $0^{\circ}\text{C} \le T_{\text{A}} \le 70^{\circ}\text{C}$ , VTerm = 4.75V. For the LX5250, DISCONNECT = L; for the LX5252, DISCONNECT = H.

Parameter	Symbol	Test Conditions	L	LX5250/52		
Farameter	Syllibol	rest conditions	Min	Тур	Max	Units
LVD Terminator Section						
		All term lines open		35	45	mA
VTerm Supply Current	LVD <sub>ICC</sub>	LX5250: DISCONNECT > 2.0V;		15	35	
		LX5252: DISCONNECT < 0.8V		15	33	μA
Common Mode Voltage	V <sub>CM</sub>		1.125	1.25	1.375	V
Offset Voltage	Vos	Open circuit between (-) and (+) terminals	100	112	125	mV
Differential Terminator Impedance	Zo	V <sub>OUT</sub> Differential = -1V to +1V	100	105	110	Ω
Common Mode Impedance	Z <sub>CM</sub>	0.5V to 2V	110	150	195	Ω
Output Canaditanes (Note 1)		LX5250: DISCONNECT > 2.0V;			,	
Output Capacitance (Note 1)	Co	LX5252: DISCONNECT < 0.8V			3	pF
Mode Change Delay	t <sub>DF</sub>	Diffsense = 1.4V to 0V	100	115	300	ms
Diffsense Section						
Diffsense Output Voltage	$V_{DIFF}$		1.2	1.3	1.4	V
Diffsense Output Source Current	I <sub>DIFF</sub>	V <sub>DIFF</sub> = 0V	5		15	mA
Diffsense Sink Current	I <sub>SINK(DIFF)</sub>	V <sub>DIFF</sub> = 2.75V	20		200	μA
Single Ended Section						
		All tem lines = Open, Master/Slave = 0V		55	75	mA
VTerm Supply Current	SE <sub>ICC</sub>	All tem lines = 0.2V, Master/Slave = 0V		250	290	mA
v reim oupply ourient	OLICC	LX5250: DISCONNECT > 2.0V;		15	35	μA
		LX5252: DISCONNECT < 0.8V				<u> </u>
Termination Output High Voltage	Vo		2.5	2.85	3.1	V
Output Current	Io	$V_{OUT} = 0.2V$	18.5	22.5	24	mA
Sink Current	I <sub>SINK</sub>	V <sub>OUT</sub> = 4V, All lines	40	65		mA
Output Capacitance (Note 1)	Co	DISC > 2.0V			3	pF
		LX5250: DISCONNECT > 2.0V;				
	$I_{DDQ}$	LX5252: DISCONNECT < 0.8V,			2	μA
Output Leakage		$V_{LINE} = 0 \text{ to } 4V, T_A = 25^{\circ}$				
Output Leakage		LX5250: DISCONNECT > 2.0V;				
	I <sub>HP</sub>	LX5252: DISCONNECT < 0.8V,		1		μΑ
		$V_{TERM}$ = Open, $V_{LINE}$ = 2.7V, $T_A$ = 25°				
Ground Driver Impedance	$Z_{G}$	I = 1mA			100	Ω



#### **PRODUCTION DATA SHEET**

#### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified, the following specifications apply over the operating ambient temperature  $0^{\circ}\text{C} \le T_{A} \le 70^{\circ}\text{C}$ , VTerm = 4.75V. For the LX5250, DISCONNECT = L; for the LX5252, DISCONNECT = H.

Parameter	Symbol	nbol Test Conditions	LX5250/52			Units
Parameter	Syllibol	rest Conditions	Min	Тур	Max	Ullits
DISCONNECT Section						
Disconnect Thresholds	V <sub>TH</sub>		0.8		2.0	V
	,	LX5250: DISCONNECT = 0V;			40	
In must Cumment	I <sub>IL</sub>	LX5252: DISCONNECT = 2.4V			10	μA
Input Current		LX5250: DISCONNECT = 2.4V;		400		nA
	IIH	LX5252: DISCONNECT = 0V		100		
MASTER/SLAVE Section						
Master/Slave Thresholds	V <sub>TH(MS)</sub>		0.8		2.0	V
Input Current	I <sub>IL(MS)</sub>	Master/Slave = 0V			10	μΑ
Input Guirent	I <sub>IH(MS)</sub>	Master/Slave = 2.4V		100		nA

Note 1: Guaranteed by design.

### **BLOCK DIAGRAM**

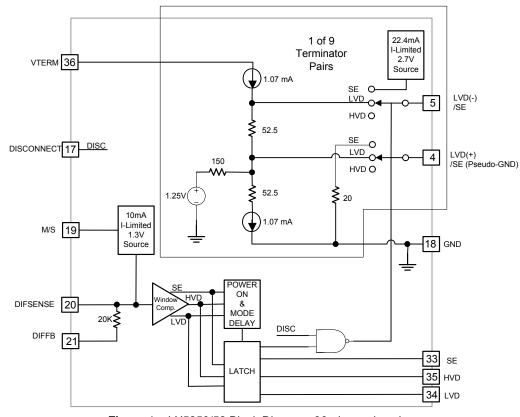


Figure 1 - LX5250/52 Block Diagram; 36-pin version shown

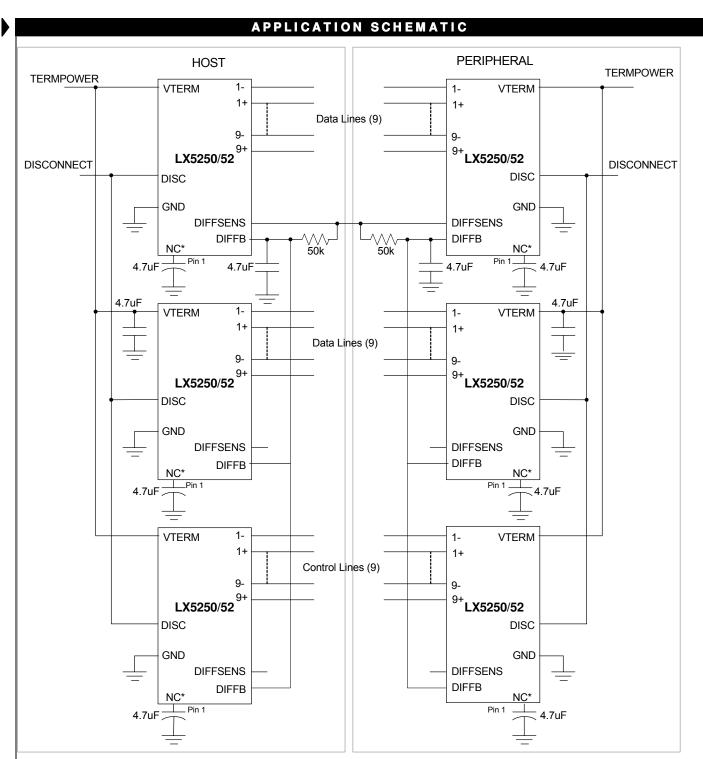


# PRODUCTION DATA SHEET

FUNCTIONAL PIN DESCRIPTION				
PIN NAME	DESCRIPTION			
1-, 2-, 3-, 4-, 5-, 6-, 7-, 8-, 9-	Negative signal termination lines for LVD mode. Signal termination lines for SE mode.			
1+, 2+, 3+, 4+, 5+, 6+, 7+, 8+, 9+	Positive signal termination lines for LVD mode. Psuedo-ground lines for SE mode.			
V <sub>TERM</sub>	Power supply pin for terminator. Connect to SCSI bus VTERM. Must be decoupled by one 4.7µF low-ESR capacitor for every three terminator devices. It is absolutely necessary to connect this pin to the decoupling capacitor through a very low impedance (big traces to PCB). Keeping distances very short from the decoupling capacitors is somewhat layout dependent and some applications may benefit from high frequency decoupling with 0.1µF capacitors at V <sub>TERM</sub> pin.			
DISCONNECT	Enables/Disables terminator. See Power Down Function Table for logic levels for LX5250 and LX5252.			
GND	Terminator ground pin. Connect to ground.			
MASTER/SLAVE	Sometimes referred to as M/S pin in this datasheet. Used to select which terminator is the controlling device. M/S pin High or Open enables the DIFFSENSE output drive. Please see MASTER/SLAVE Function Table.			
DIFFSENSE	This is a dual function pin. It drives the SCSI bus DIFFSENS line. It is also the sense pin to detect the SCSI bus mode (LVD, SE, or HVD). DIFFSENSE output drive can be disabled with low level on the M/S pin. Please see DIFFSENSE and MASTER/SLAVE Function Tables. Internally connected to DIFFB pin through a $20K \Omega$ resistor.			
DIFFB	Internally connected to DIFFSENSE pin through a 20K $\Omega$ resistor. It can be used as a mode sense pin when the device is non-controlling terminator (M/S is low). An RC filter (50K $\Omega$ resistor & 4.7 $\mu$ F) is not required on the LX5250 as it has an internal timer.			
SE	Single-Ended output; when High, terminator is operating in SE mode.			
LVD	Low Voltage Differential output; when High, terminator is operating in LVD mode.			
HVD	High Voltage Differential output; when High, terminator is operating in HVD mode.			
HEATSINK	Attached to die mounting pad, but not bonded to GND pin. Pins should be considered a heat sink only, and not a true ground connection. It is recommended that these pins be connected to ground, but can be left floating.			



#### **PRODUCTION DATA SHEET**



\*The capacitor on pin 1 can be placed on the LX5250CDB, LX5250CPW, or LX5252CDB to be pin-compatible with other devices, but is not required.

Figure 2 – Application Diagram

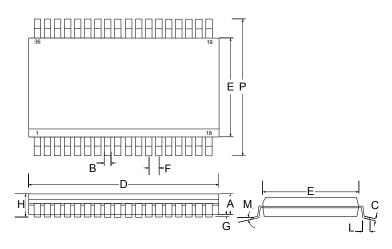


**PRODUCTION DATA SHEET** 

## MECHANICAL DRAWINGS

### $\mathbf{DR}$

# 36-Pin Quarter Size Outline Package (QSOP)

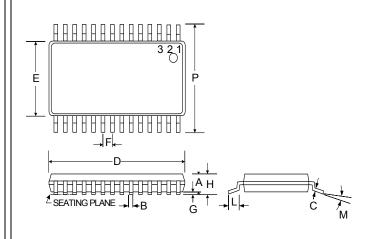


Dim	MILLIMETERS		INC	HES	
Dilli	MIN	MAX	MIN	MAX	
Α	2.14	2.54	0.084	0.100	
В	0.29	0.51	0.011	0.020	
С	0.23	0.32	0.009	0.0125	
D	15.20	15.40	0.598	0.606	
E	7.40	7.60	0.291	0.299	
F	0.80	BSC	0.031	BSC	
G	0.10	0.30	0.004	0.012	
Н	2.44	2.64	0.096	0.104	
L	0.51	1.01	0.020	0.040	
M	0°	8°	0°	8°	
Р	10.11	10.51	0.398	0.004	
*LC	_	0.10	_	0.004	

<sup>\*</sup>Lead Coplanarity

# PW

# 28-Pin Thin Small Shrink Outline (TSSOP)



Dim	MILLIM	IETERS	INC	HES
Dilli	MIN	MAX	MIN	MAX
Α	0.85	0.95	0.033	0.037
В	0.19	0.30	0.007	0.012
С	0.09	0.20	0.003	0.008
D	9.60	9.80	0.378	0.390
Е	4.30	4.50	0.169	.176
F	0.65	BSC	0.025	BSC
G	0.05	0.15	0.002	0.005
Н	_	1.10	_	0.043
L	0.50	0.75	0.020	0.030
M	0°	8°	0°	8°
Р	6.25	6.50	0.246	0.256
*LC	_	0.10	_	0.004

#### Note:

 Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.



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NOTES

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